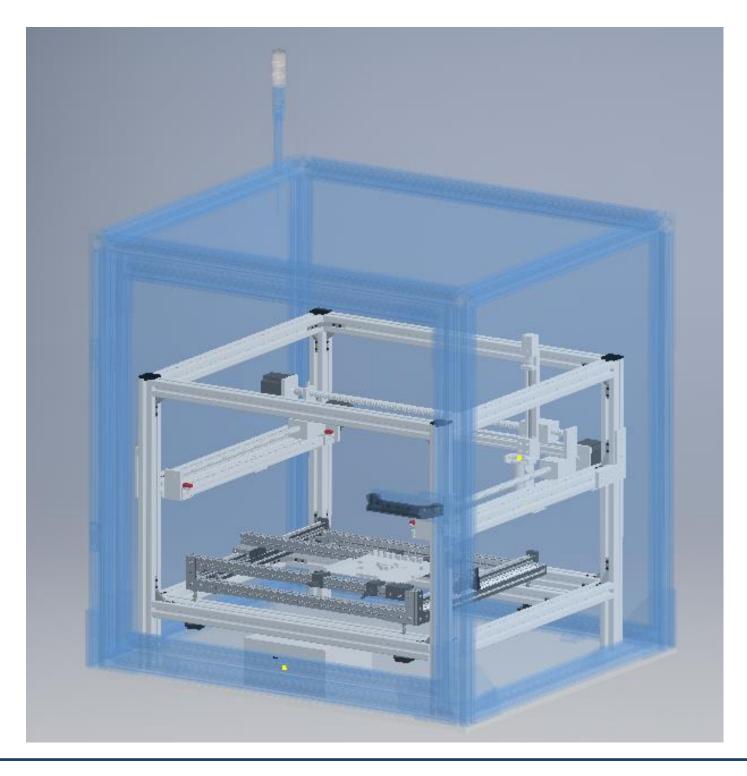


Abstract

This project was a collaboration between BAE Systems Inc., a Fort Wayne based company that assembles specialty circuit boards, and Trine University Mechanical Engineering students. The goal of this project is to design and build an automated machine that will lay a bead of silicone sealant along the edge of components on a circuit card assembly.

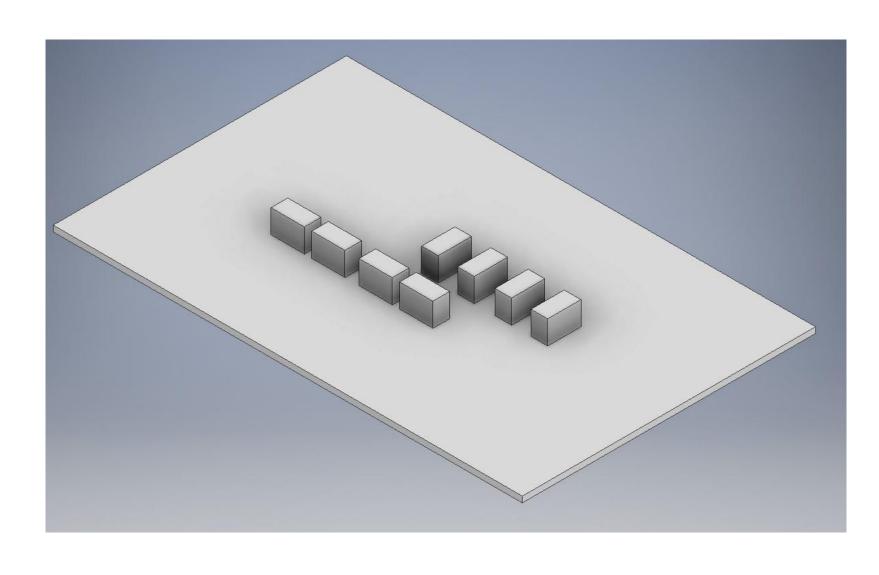
Design Solution

The final design solution is a fully customized 3 axis machine the meets all the requirements given.



Testing and Validation

- Test 1: Initial Coding • Used to determine how the coding language will work



BAE Circuit Card Sealant Machine

Dalton Bell, Zachary Hoehn, Eli Pfotenhauer, Alex Taylor, Josh Williams Mechanical and Aerospace Engineering Advisor: Dr. Kendall Teichert

Customer Needs and Requirements

- Overall size must be roughly 30" x 30"
- Must fit a maximum CCA size of 18" x 20"
- Must follow BAE safety protocols ullet
- Machine must use 30CC RTV Cartridges
- Must cost less than \$15,000

Cutting Frame



Aluminum Extrusion Frame

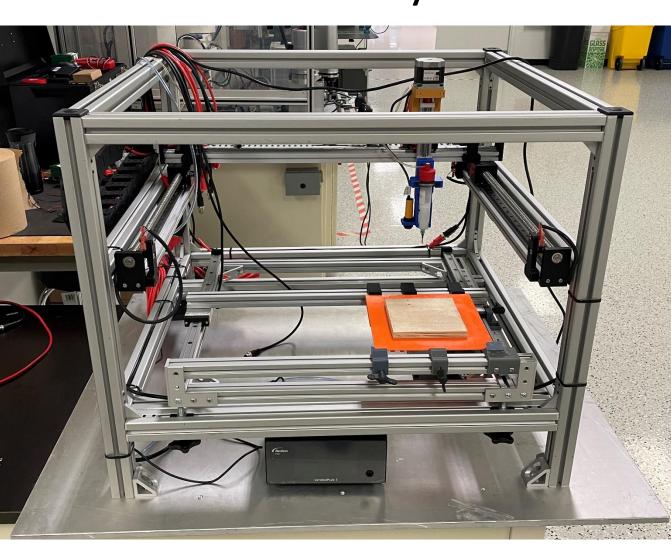
Test 2: Simple Test Board • Simple components to track needle position

Test 3: Final Board

- Components from BAE CCA
- RTV applied to all components



Assembly



- 90° Aluminum Gussets
- Attach to Aluminum Plate

Concept Selection • Screw Drives • Nordson Dispenser Hakko Board Cradle





Dispenser Integration

Integration of Dispenser with **Operating System**



Acknowledgments

We would like to acknowledge BAE Systems, Innovation One, and our lab manager, Joe Thompson



References: Board Holder: <u>Metcal BH-2000 - Board Holder (hisco.com</u>) Screw Drive Assembly: <u>Cartesian Robot XYZ Stage Positioning Rail Guide Linear Gantry</u> <u>System - Fuyu Technology Co., Ltd. (fuyumotion.com)</u> Dispenser: Precision Fluid Dispensers | Nordson EFD

